

General Description

The WSF70P03 is the highest performance trench P-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSF70P03 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

Product Summery

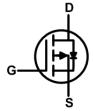
BVDSS	RDSON	ID
-30V	7.5mΩ	-65A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

TO-252 Pin Configuration





Absolute Maximum Ratings

	Rating			
Symbol	Parameter	10s	Steady State	Units
V_{DS}	Drain-Source Voltage		30	V
V_{GS}	Gate-Source Voltage	<u>±</u>	20	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ -10V ¹		57	Α
I _D @T _C =100℃	Continuous Drain Current, V _{GS} @ -10V ¹		36	Α
I _D @T _A =25℃	Continuous Drain Current, V _{GS} @ -10V ¹	-17.8	-11.3	Α
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ -10V ¹	-14.2	-9	Α
I _{DM}	Pulsed Drain Current ²	-180		Α
EAS	Single Pulse Avalanche Energy ³ 408		08	mJ
I _{AS}	Avalanche Current -55.4		Α	
P _D @T _C =25°C	Total Power Dissipation ⁴ 52.1		W	
P _D @T _A =25°C	Total Power Dissipation ⁴	5	2	W
T _{STG}	Storage Temperature Range	-55 t	-55 to 150	
TJ	Operating Junction Temperature Range	-55 t	-55 to 150	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹		62	°C/W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹ (t ≤10s)		25	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case ¹		2.4	°C/W



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-30			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25 $^{\circ}\!$		-0.018		V/°C
В	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-30A		7.5	9.5	0
R _{DS(ON)}	Static Diain-Source On-Resistance	V _{GS} =-4.5V , I _D =-15A		12	16	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V _{GS} =V _{DS} . I _D =-250uA	-1.0	-1.6	-2.5	٧
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	— V _{GS} −V _{DS} , I _D −-250uA		5.04		mV/℃
	Drain Source Leakage Current	V_{DS} =-24V , V_{GS} =0V , T_J =25 $^{\circ}$ C			1	
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-24V , V _{GS} =0V , T _J =55℃			5	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 20 V$, V_{DS} = $0 V$			±100	nA
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-30A		26.4		S
Qg	Total Gate Charge (-4.5V)			33		
Q_gs	Gate-Source Charge	V _{DS} =-15V , V _{GS} =-4.5V , I _D =-15A		10.7		nC
Q _{gd}	Gate-Drain Charge			12.8		
T _{d(on)}	Turn-On Delay Time			8		
T _r	Rise Time	V_{DD} =-15V , V_{GS} =-10V , R_{G} =3.3 Ω , I_{D} =-15A		17.8		
T _{d(off)}	Turn-Off Delay Time			78.4		ns
T _f	Fall Time			43.6		
C _{iss}	Input Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		3448		
Coss	Output Capacitance			508		pF
C _{rss}	Reverse Transfer Capacitance			421		

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	V _{DD} =-25V , L=0.1mH , I _{AS} =-30A	120			mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			-18	Α
I _{SM}	Pulsed Source Current ^{2,6}				-180	Α
V_{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25℃			-1.2	V
t _{rr}	Reverse Recovery Time	IF=-15A , dI/dt=100A/μs ,		29		nS
Q_{rr}	Reverse Recovery Charge	T _J =25℃		15		nC

Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper ,t<10sec.
- 2.The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =-25V, V_{GS} =-10V,L=0.1mH, I_{AS} =-30A
- 4. The power dissipation is limited by 150 ℃ junction temperature
- 5. The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

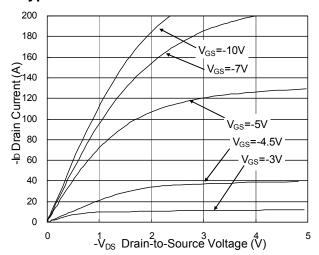


Fig.1 Typical Output Characteristics

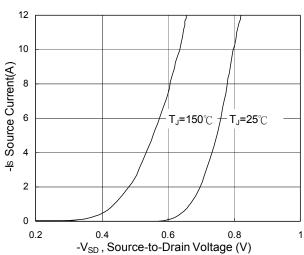


Fig.3 Forward Characteristics Of Reverse

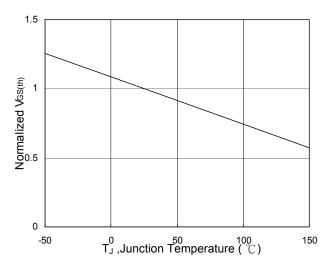


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

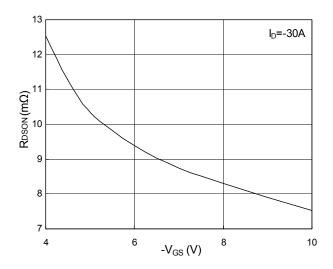


Fig.2 On-Resistance v.s Gate-Source

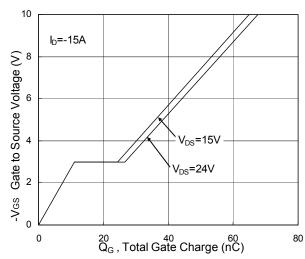


Fig.4 Gate-Charge Characteristics

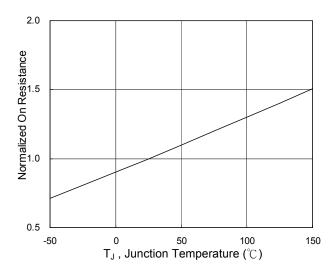
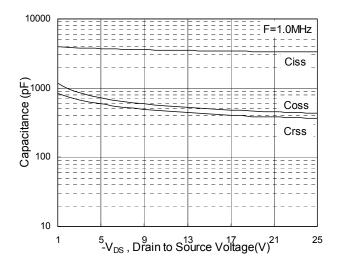


Fig.6 Normalized R_{DSON} v.s T_J





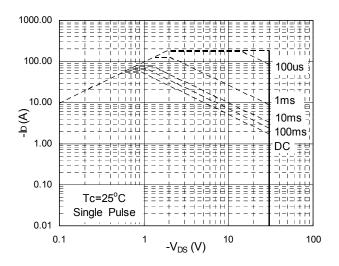


Fig.7 Capacitance

Fig.8 Safe Operating Area

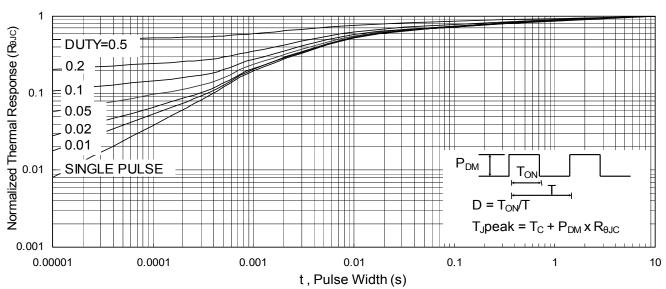


Fig.9 Normalized Maximum Transient Thermal Impedance

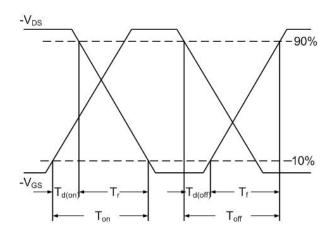


Fig.10 Switching Time Waveform

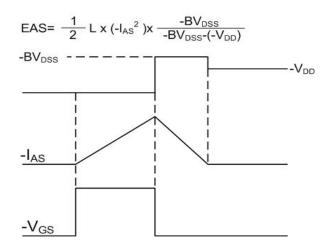


Fig.11 Unclamped Inductive Switching Waveform



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